Sponsored by

Technically Sponsored by

杭州市北京航空航天大学国际创新研究院
（北京航空航天大学国际创新学院）
HANGZHOU INTERNATIONAL INNOVATION INSTITUTE OF BEIHANG UNIVERSITY

IEEE CASS FLAGSHIP CONFERENCES COLOCATED FOR THE FIRST TIME

IEEE CASS 旗舰会议 · 首次联合举办

SPONSORSHIP PROSPECTUS 赞助招商

AICAS & APCCAS

September 20–24, 2027

Midtown Shangri-La · Hangzhou, China

2027 年 9 月 20–24 日 · 中国杭州城中香格里拉大酒店



AICAS 2027

IEEE International Conference on Artificial Intelligence Circuits and Systems

IEEE 人工智能电路与系统国际会议

APCCAS 2027

IEEE Asia Pacific Conference on Circuits and Systems

IEEE 亚太电路与系统会议

Sponsorship Prospectus

赞助招商手册

Two flagship conferences of IEEE CASS, one week in Hangzhou. Sponsor once and reach the full circuits, AI-hardware and systems community.

IEEE CASS 两大旗舰会议，同聚杭州一周。一次赞助，触达电路、AI 硬件与系统领域的完整学术与产业社群。

SHARED 共享议程

Keynotes 主旨报告 | **Tutorials** 专题教程 | **Banquet** 联合晚宴

Contact: frannie@youngac.cn
赞助咨询

Welcome Message 欢迎辞

We are pleased to invite your organization to sponsor **AICAS 2027** and **APCCAS 2027**, two flagship conferences of the IEEE Circuits and Systems Society, held together for the first time from 20 to 24 September 2027 at the Midtown Shangri-La, Hangzhou, China.

The co-located week brings together researchers, engineers, industry leaders and students working across the full stack of intelligent hardware — from devices and circuits to AI accelerators, computing-in-memory and complete systems. The two communities share keynotes, tutorials and a banquet, so a single sponsorship puts your organization in front of both audiences, in one venue, in one week.

我们诚挚邀请贵单位成为**AICAS 2027**与**APCCAS 2027**的赞助合作伙伴。AICAS 2027与APCCAS 2027 将于2027年9月20日至24日在中国杭州城中香格里拉酒店召开，这是IEEE电路与系统学会(IEEE CASS)旗下的两大旗舰会议首次联合举办。两场会议将汇聚智能硬件领域的专家学者、工程师、行业领军人物及青年学子，覆盖器件与电路、人工智能加速器、存内计算及完整系统等多个前沿方向。本次联合将共享大会主旨报告、专题教程及会议晚宴等重要活动，为赞助合作伙伴搭建跨领域交流与合作的平台。一次赞助，即可同时链接两大会议的专业群体，在同一会场、同一周内实现双重品牌曝光与交流机遇。

General Chairs · 大会主席

Amara Amara
Beihang University

Weisheng Zhao
Beihang University

Why sponsor 赞助价值

- **Two flagship audiences in one week**
  一周覆盖两大旗舰会议受众
- **Visibility to 600+ expected participants**
  面向预计 600 余名参会者
- **Leadership in AI hardware and circuits**
  彰显在 AI 硬件与电路领域的领先地位
- **Direct access to your technical community**
  精准对接目标技术群体
- **Promotion across both conferences**
  两大会议联合宣传，曝光倍增
- **Exhibit and distribute your materials**
  展位展示与宣传资料派发
- **Meet the next generation of chip and AI hardware engineers**
  结识芯片与 AI 硬件领域的新一代人才，助力企业招聘

Conference Information 会议信息

Conferences 会议名称	IEEE International Conference on Artificial Intelligence Circuits and Systems (AICAS 2027) IEEE Asia Pacific Conference on Circuits and Systems (APCCAS 2027) IEEE 人工智能电路与系统国际会议 · IEEE 亚太电路与系统会议
Dates 会议日期	20 (Mon) – 24 (Fri) September 2027 2027 年 9 月 20 日（周一）至 24 日（周五）
Venue 会议地点	Midtown Shangri-La, Hangzhou, China 中国 · 杭州城中香格里拉大酒店
Sponsored by 主办	IEEE Circuits and Systems Society IEEE 电路与系统学会
Technically sponsored by 承办	Hangzhou International Innovation Institute, Beihang University 北京航空航天大学杭州国际创新研究院
Expected participants 预计参会人数	600+ across both conferences 两会合计 600 人以上
Official language 官方语言	English 英语
Official website 官方网站	https://2027.ieee-aicas.org https://2027.ieee-apccas.org

Programme at a glance 日程概览

20 Sep Monday · 周一	21 Sep Tuesday · 周二	22 Sep Wednesday · 周三	23 Sep Thursday · 周四	24 Sep Friday · 周五
AICAS	AICAS	SHARED DAY · 联合日	APCCAS	APCCAS
Registration 注册	Technical sessions 技术分会	Joint opening & keynotes 联合开幕式与主旨报告	Opening 开幕	Technical sessions 技术分会
Opening 开幕	Special and industry session 特别分会及产业专场	Joint tutorials 联合专题教程	Technical sessions 技术分会	Awards & closing 颁奖与闭幕
Technical sessions 技术分会	Exhibition 展览	Banquet 联合晚宴	Special and industry session 特别分会及产业专场	
Exhibition 展览			Exhibition 展览	

*Preliminary programme, subject to change. 以上为初步日程，如有调整以最终版本为准。

Topics, Host City & Chairs 会议主题、举办城市与主席

Topics of interest 征稿主题

AICAS 2027

- Hardware for embodied AI: perception, sensor fusion, motion control and robotics processors
  具身智能硬件：感知、传感器融合、运动控制及机器人处理器
- Accelerators for agentic AI, large language models and multimodal foundation models
  面向智能体人工智能、大语言模型及多模态基础模型的加速器
- Computing-in-memory, near-memory and processing-in-sensor architectures
  存内计算、近存计算及传感器内处理架构
- Emerging devices for AI: spintronic, resistive, ferroelectric, phase-change and photonic
  面向人工智能的新兴器件：自旋电子器件、阻变器件、铁电器件、相变器件及光子器件
- Neuromorphic and spiking circuits and systems
  类脑计算与脉冲神经网络电路及系统
- Edge and on-device AI: low-power inference, on-chip learning and continual learning
  边缘与端侧人工智能：低功耗推理、片上学习及持续学习
- Hardware–software co-design, compilers and AI for EDA
  软硬件协同设计、编译器及人工智能辅助电子设计自动化
- Chiplets, 3D integration and memory systems for AI
  面向人工智能的芯粒、三维集成及存储系统
- Trustworthy, secure and reliable AI hardware
  可信、安全与可靠的人工智能硬件
- AI circuits and systems for healthcare, mobility, manufacturing and smart cities
  面向医疗健康、智能出行、制造业及智慧城市的人工智能电路与系统

APCCAS 2027

- Artificial intelligence circuits, systems and applications
  人工智能电路、系统与应用
- Digital integrated circuits and systems
  数字集成电路与系统
- Analog and mixed-signal circuits and systems
  模拟与混合信号电路与系统
- Power and energy circuits and systems
  功率与能源电路与系统
- Biomedical circuits and systems
  生物医学电路与系统
- Sensory circuits and systems
  传感电路与系统
- RF and communications circuits and systems
  射频与通信电路与系统
- Beyond CMOS: nanoelectronics and hybrid systems integration
  超越 CMOS：纳米电子学与混合系统集成
- Neural and nonlinear circuits and systems
  神经与非线性电路与系统

Why Hangzhou 为何选择杭州

Digital economy hub
A leading centre for internet, AI and intelligent manufacturing.
互联网、人工智能与智能制造重镇

Binjiang High-tech Zone
A dense cluster of technology companies and research institutes.
滨江高新区，科技企业与研究机构高度集聚

Yangtze River Delta
45–60 minutes to Shanghai by high-speed rail.
长三角核心城市，高铁 45–60 分钟直达上海

General Chairs 大会主席

AA
Amara Amara
Hangzhou International Innovation Institute, Beihang University, China

WZ
Weisheng Zhao
Beihang University, China

04

Sponsorship Packages 赞助方案

PRICES IN USD
CNY FOR REFERENCE · 人民币仅供参考

Benefits 赞助权益	BRONZE 铜牌 $1,000 ≈ ¥7,000	SILVER 银牌 $3,000 ≈ ¥21,000	GOLD 金牌 $6,000 ≈ ¥42,000	PLATINUM 铂金 $12,500 ≈ ¥87,500	DIAMOND 钻石 $19,000 ≈ ¥133,000
Full conference registrations 全额注册名额	0	1	2	4	8
A4 advertisement inserted in delegate bag A4宣传页广告入袋	✓	✓	✓	✓	✓
Full-page A4 advertisement in final programme 会议日程插入A4整页宣传页	✓	✓	✓	✓	✓
Listed as exhibitor / promotional sponsor on printed materials 会议印刷物料上作为展商宣传	✓	✓	✓	✓	✓
One commercial exhibition booth 商业展位一个 one backboard, one table, two chairs	—	✓	✓	✓	✓
Company logo with link on conference website 会议官网企业标志及链接	—	✓	✓	✓	✓
Company logo in final programme 会议日程册企业标志	—	✓	✓	✓	✓
Promotional giveaway inserted in delegate bag 参会资料袋企业宣传礼品	—	—	✓	✓	✓
Company logo on conference opening slide 开幕式幻灯片企业标志	—	—	✓	✓	✓
Special thanks at official events 官方活动特别鸣谢	—	—	✓	✓	✓
Industry sessions included 产业专场 90 min each • room and AV included • participants must register	—	—	—	1	2
Company logo on welcome sign 欢迎指示牌企业标志	—	—	—	✓	✓
Company logo on coffee-break signboard 茶歇区标识牌企业标志	—	—	—	✓	✓
Complimentary use of one meeting room 免费使用会议室一间	—	—	—	—	✓
Free-standing banner at registration area 注册区独立展架	—	—	—	—	✓
One-minute company video at the banquet 联合晚宴一分钟企业宣传视频	—	—	—	—	✓

Benefits apply across both AICAS 2027 and APCCAS 2027. CNY amounts are indicative at USD 1 = CNY 7.
所有权益同时适用于 AICAS 2027 与 APCCAS 2027。人民币金额按 1 美元 = 7元人民币折算。

How to Apply 申请指南

1

Choose a package

Select the tier that fits your goals.
选择适合贵单位的赞助级别

2

Submit the form

Complete the online application via the link or QR code.
通过链接或二维码在线提交申请表

3

Confirm & pay

Receive the invoice and confirm with your deposit.
收到发票后支付定金以确认赞助

Terms 条款说明

- The applicant is responsible for any bank service charges or money-transfer fees.
  银行手续费及汇款费用由申请方承担。
- Sponsorship fees are subject to change by the organizing committee.
  组委会保留调整赞助费用的权利。
- Sponsor and exhibition-booth locations are allocated first by sponsorship tier, then by deposit payment date, and lastly by application date.
  赞助商及展位位置的分配依次按赞助级别、定金支付日期和申请日期确定。

CONTACT · 联系我们

AICAS & APCCAS 2027 Sponsorship

frannie@youngac.cn

Application form: https://iconf.young.ac.cn/kKUIe

See you in Hangzhou!

期待与您相聚杭州